

Chemical Usage Form

THIS FORM MUST BE COMPLETED BY ALL USERS OF INRF THAT ACCESS WET PROCESSING AREAS

User Name: _____

Check all Classes of Hazardous Material that apply, see Hazardous Material SOP for INRF at:
http://www.ehs.uci.edu/programs/sop_library/index.html

Acids	Toxic Compounds	Toxic Gases
Hydrofluoric Acid	Water Reactive Chemicals	Reactive or Explosive Chemicals
Ammonium Fluoride	Pyrophoric Substances	Carcinogens
Bases	Cryogenic Fluids	
Solvents	Asphyxiant Gases	
Oxidizers	Flammable Gases	

Other, please explain:

Process (Check all that apply, see: <http://www.inrf.uci.edu/facility/sop/wet-dry/>)

Alcohol NAOH	Glass Etch	Nickel Etch
Si Etch usin KOH	Gold Etch	Silicon RCA-1
Buffered Oxide Etch	HF (2%) Dip	Silicon RCA-2
Nickel Electroless Plating	Isotropic Si Etch using HNA	Silicon Solvent Clean

Process name/title (Attach SOP):

PI/Supervisor Certification:

I certify that this individual has received training specific to the hazards involved in working with the material or process checked off, including work area decontamination and emergency procedures. .

Authorized PI Signature _____ Date _____

User Acknowledgement:

By checking the applicable boxes above and signing below, I acknowledge that I have read and understood the SDS and Standard Operating Procedure (SOP) for each chemical and process.

I have located the SDS on file with INRF/BiON at: <http://www.inrf.uci.edu/msds/>.

The chemical I plan to use is not found in the INRF online SDS Database. I will submit a chemical request form (<http://www.inrf.uci.edu/safety/standard-procedures/>) and SOP (if applicable).

User Signature _____ Date _____